

Fanless Atom System Features Small Footprint



Logic Supply introduced an ultra-slim, fanless Intel Atom system housed in a ruggedized, small-footprint enclosure. A flexible, efficient solution for seamless deployment in industrial environments, public access areas, or remote locations, the SolidLogic Atom JT01 is designed to offer reliable, stable operation while consuming minimal power. The JT01 features an Intel Atom N270 processor paired with the Intel 945GSE embedded chipset offering a combined thermal design power (TDP) of less than 11 W. The system outputs DVI, VGA, Gb LAN, five USB 2.0 ports, and two RS-232 COM as well as wireless networking capabilities. The mainboard is housed in a solid steel and extruded aluminum chassis that can be conveniently mounted to a variety of surfaces. The chassis is solid black and is less than 1.5" thick, making it easy to tuck the system away and disguise it from view in high-traffic areas. Using heat sinks with solid copper cores to disperse heat to the extruded aluminum top panel of the case, the entire system exhibits exceptional thermal management and maintains silent, uninterrupted operation over time. The mainboard has built-in mounting for installation of a USB storage device, allowing for configuration of a completely solid state (no moving parts) system.

Logic Supply

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